

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	245828	probe	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/13 14:43
2	BRS	L2	6224	1 near8 (extend\$4 or cantilever or beyond) near8 (edge or sidewall or end)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/13 14:45
3	BRS	L3	17486	1 same (extend\$4 or cantilever or beyond) same (edge or sidewall or end)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/13 14:46
4	BRS	L4	75	1 same (recess\$3 or beam\$3 or lead\$3 or extension\$3) same (sacrific\$8)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/13 15:03
5	BRS	L5	177	2 same (damage or fractur\$4 or break\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/13 15:17

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L6	730	3 same (damage or fracture\$4 or break\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/13 15:17
7	BRS	L7	553	6 not 5	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/13 15:17
8	BRS	L8	35	7 same (form\$4 or deposit\$4 or grow\$4) same (recess\$3 or hole\$3 or trench\$3 or channel\$3)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/13 15:28
9	BRS	L9	3294	(recess\$3 or hole\$3 or trench\$3 or channel\$3) same (substrate or substrates or wafer or wafers) same sacrific\$8	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/13 15:44
10	BRS	L10	27	9 same probe	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/13 15:53

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L11	342	9 and probe	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/13 15:54
12	BRS	L12	315	11 not 10	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/13 15:54